

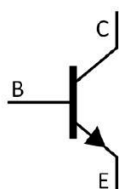
/ Descriptions

SOT-23 NPN Silicon NPN transistor in a SOT-23 Plastic Package.

/ F

Low current, Low voltage, HF Product.

General purpose amplifier and switching.



PIN 1 Base PIN 2 Emitter PIN 3 Collector

/ h_{FE} Classifications & Marking

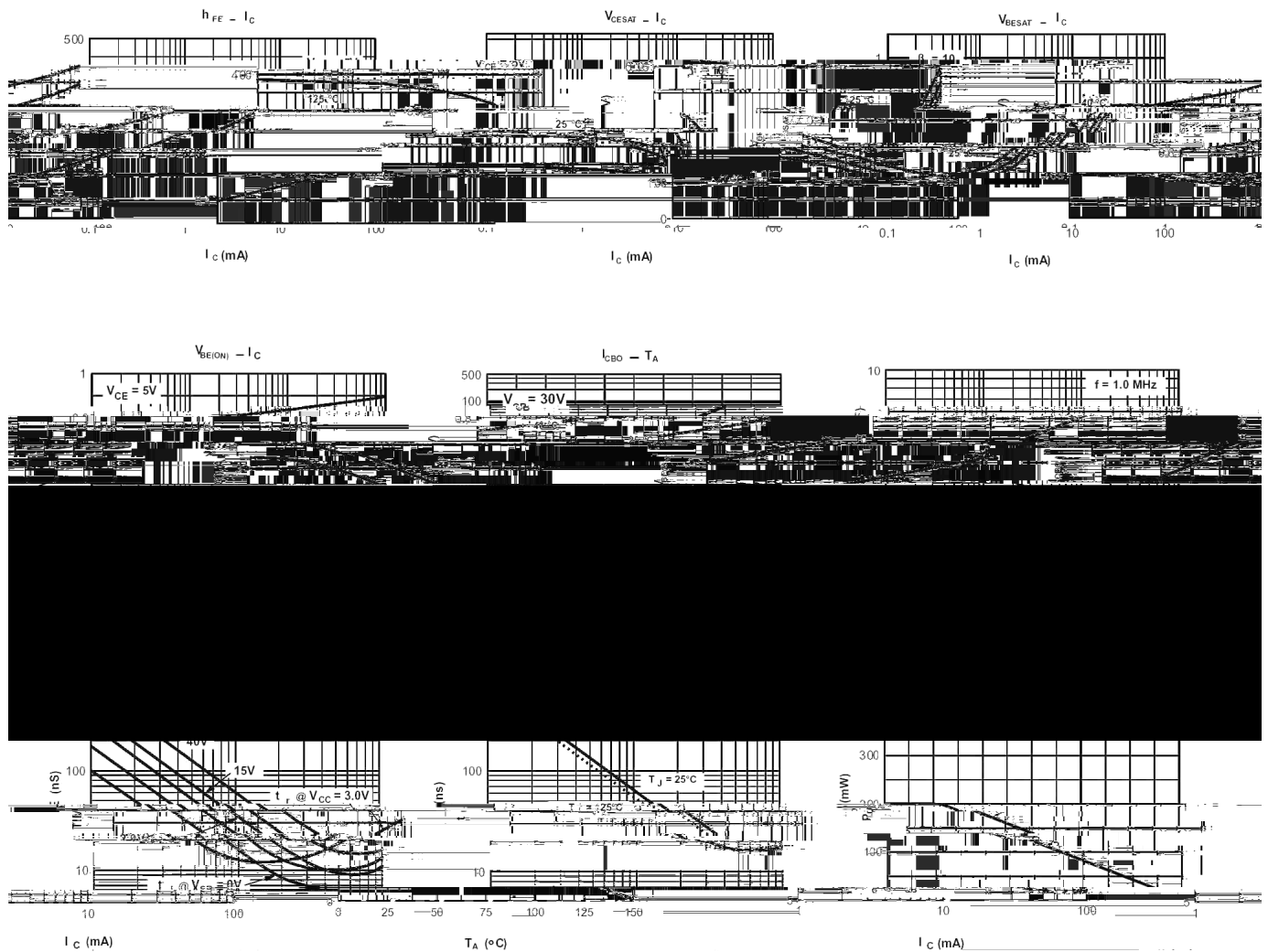
h_{FE} Range	100~300
Marking	• H1A

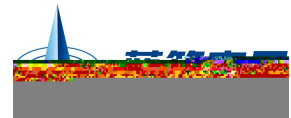
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	60	V
Collector to Emitter Voltage	V_{CEO}	40	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current	I_C	200	mA
Collector Power Dissipation	P_C	200	mW
Collector Power Dissipation	$*P_C$	350	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

* 7×5×0.6mm *When mounted on a 7×5×0.6mm ceramic board

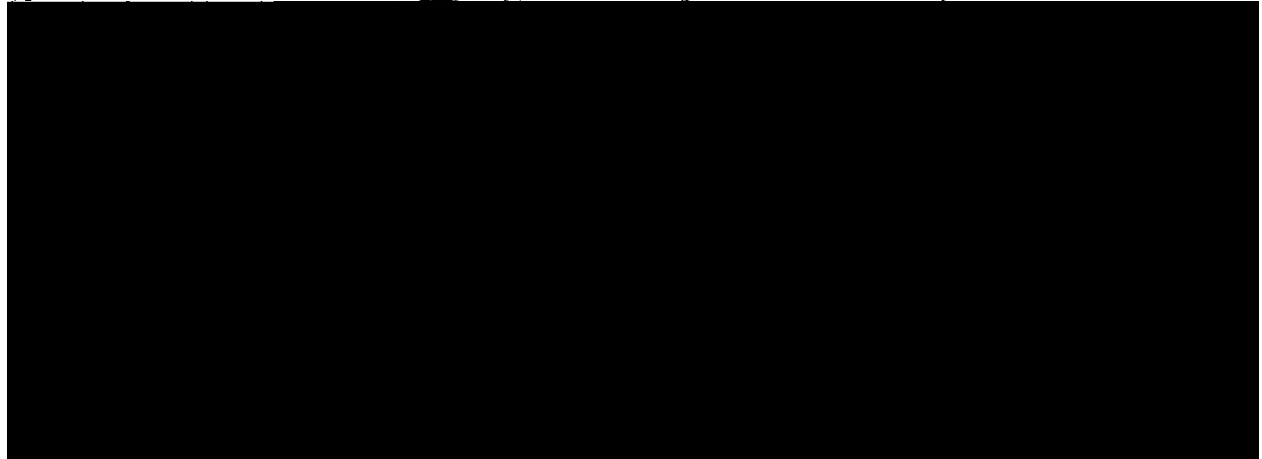
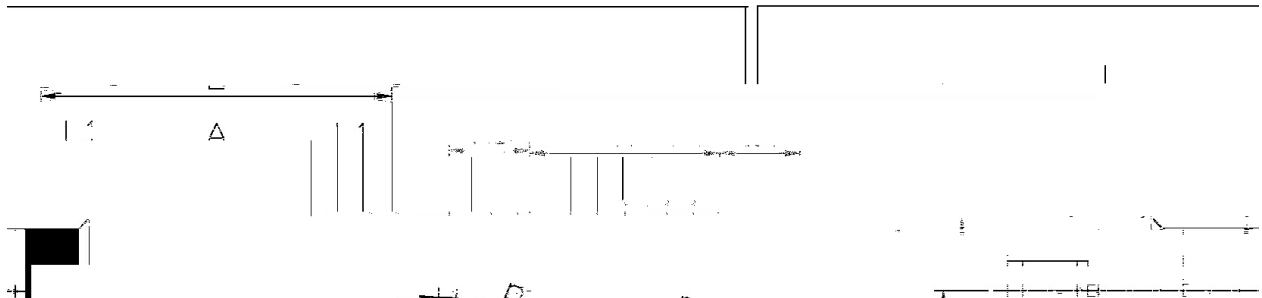
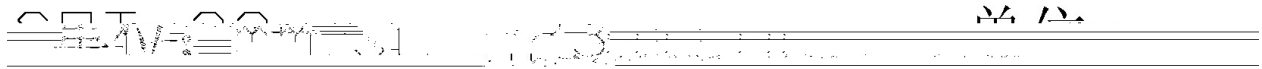
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage						

/ Electrical Characteristic Curve



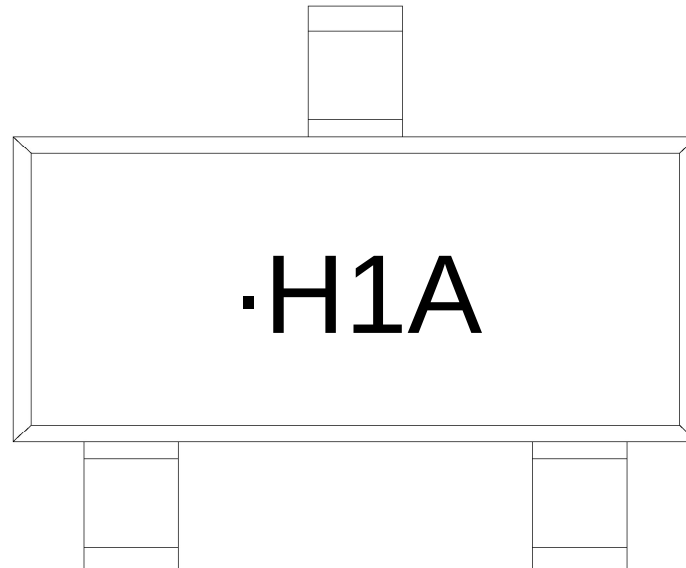


/ Package Dimensions



Symbol	Dimensions in Millimeters		Symbol	Dimensions in Millimeters	
	Min	Max		Min	Max
	2.0	2.7		0.65	0.91
D	0.45	0.65	C	0.91	1.20
A	1.50	1.70	L	0.35	0.50
B	2.70	3.10	K	0	0.20
E	1.70	2.10	M	0.20	0.25
E1	0.85	1.05	P	7°	
	0.35	0.55			

/ Marking Instructions



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H

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Note:

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Identify

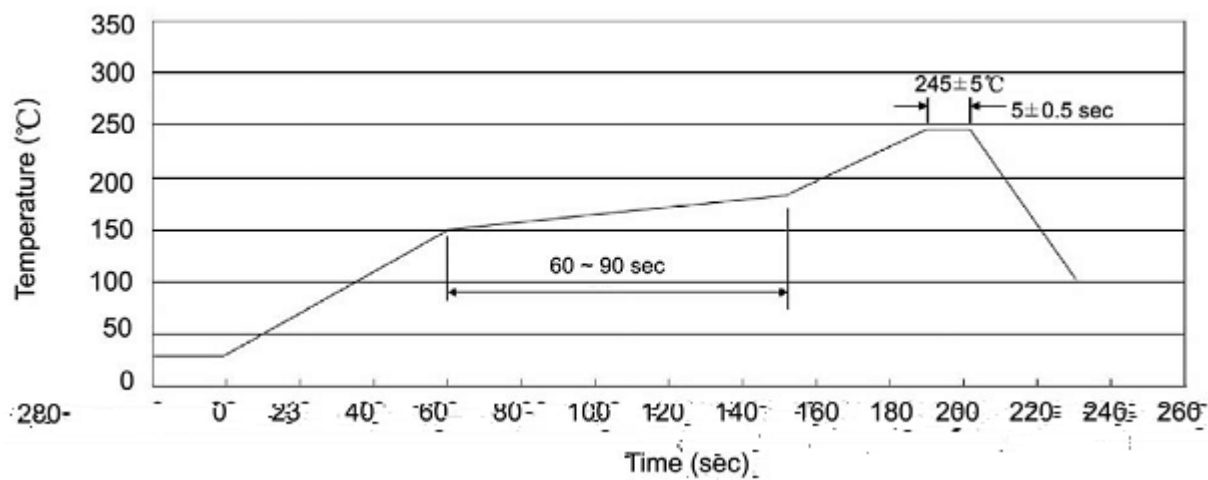
H

Company Code

1A

Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat